SLURRY COMPOSITION FOR FINAL POLISHING OF SILICON WAFERS AND METHOD FOR FINAL POLISHING OF SILICON WAFERS USING THE SAME


## ABSTRACT OF THE DISCLOSURE

Disclosed is a slurry composition for final polishing of silicon wafers to achieve mirror surfaces of the wafers. The slurry composition can include deionized water, abrasive particles, a pH-adjusting agent, a water-soluble thickener, an acetylene surfactant, and a heterocyclic amine. The particle diameter of the abrasive particles and the contents of the components can be selected so that the slurry composition can markedly reduce the number of LLS defects having a size larger than about 50 nm formed on the surface of wafers, and greatly reduce the haze and microroughness of wafer surfaces.